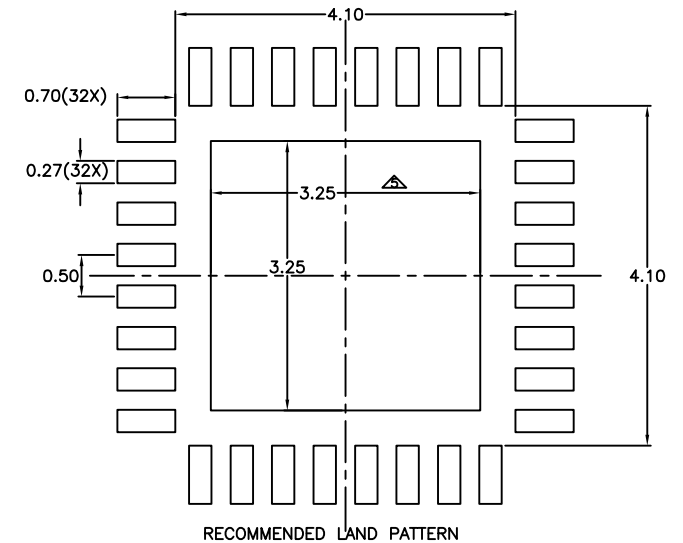
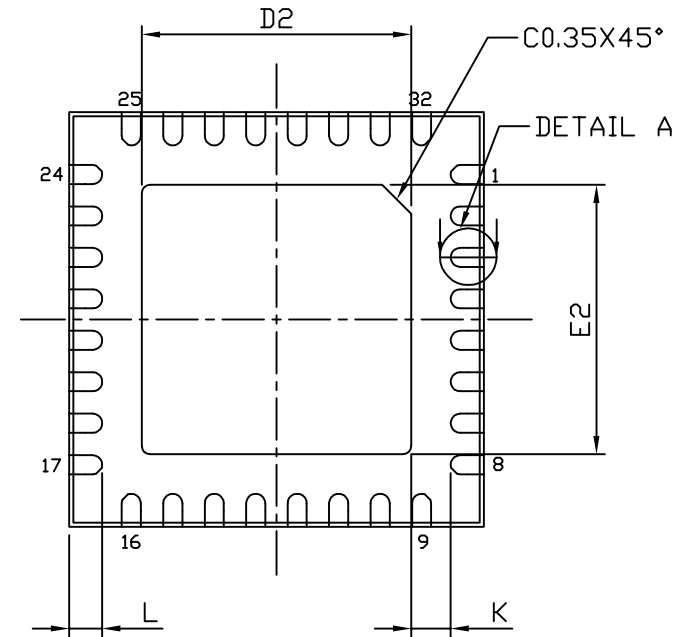
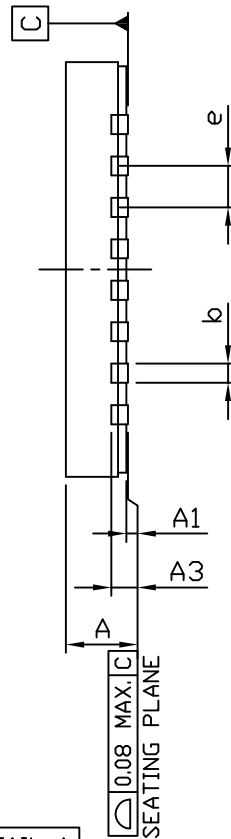
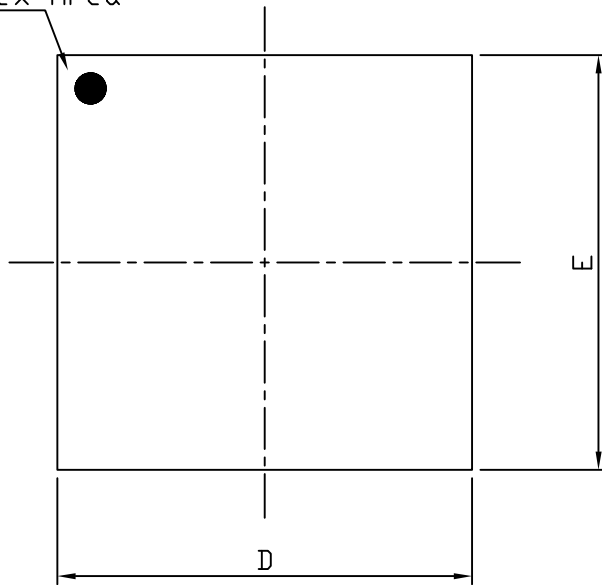
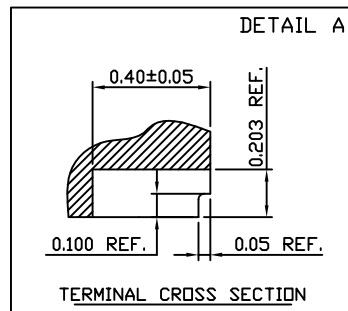


PIN1
Index Area



SYMBOLS	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.203 REF.		
b	0.18	0.25	0.30
D	4.90	5.00	5.10
E	4.90	5.00	5.10
e	0.50 BSC		
L	0.35	0.40	0.45
K	0.20	—	—
D2	3.20	3.25	3.30
E2	3.20	3.25	3.30



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220.
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

DIODES
INCORPORATED

PERICOM A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 11/23/17

DESCRIPTION: 32-Contact, TQFN 5x5mm

PACKAGE CODE: ZHQ (ZHQ32)

DOCUMENT CONTROL #: PD-2234

REVISION: --